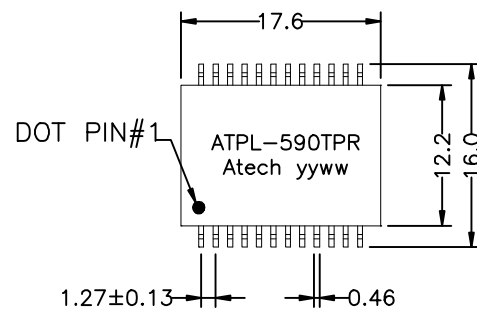
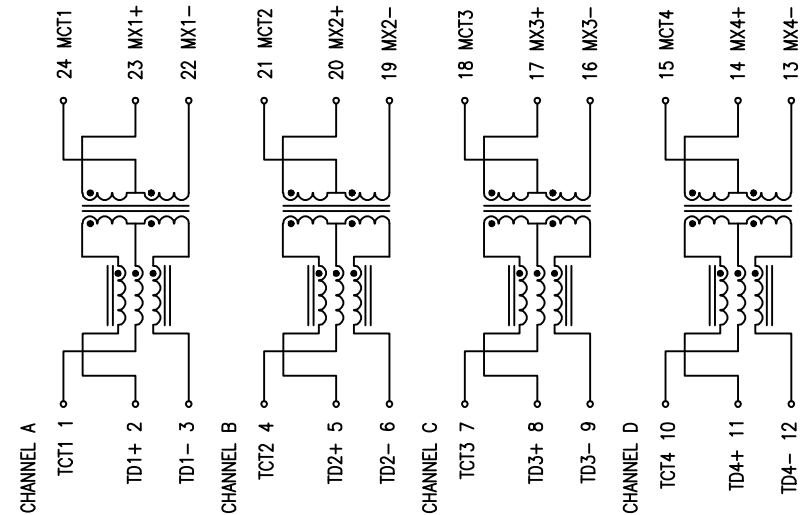


SUGGESTED PAD LAYOUT



* RoHS COMPLIANT

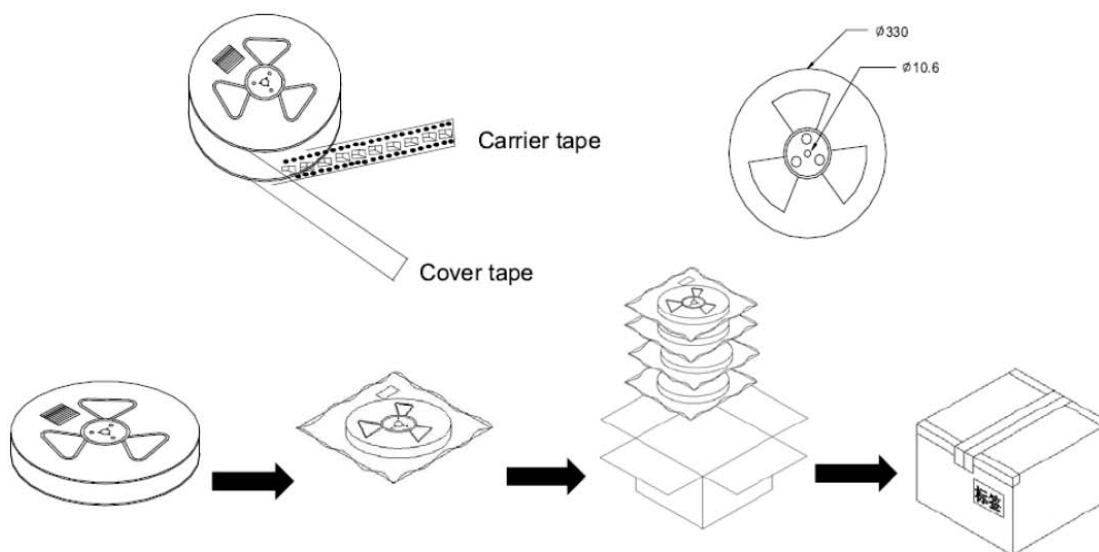
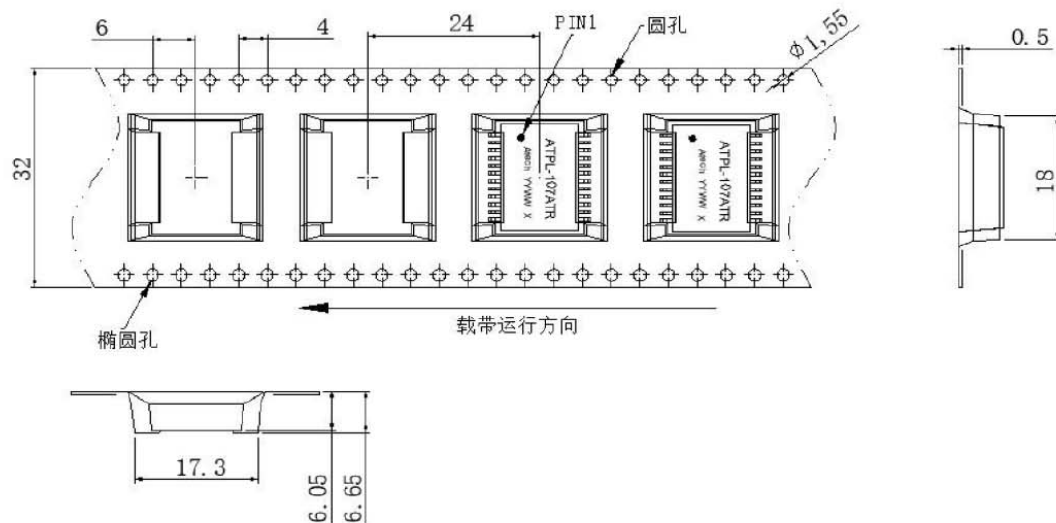
ELECTRICAL CHARACTERISTICS @25°C :

- INSULATION HI-POT : 1500 Vrms/1mA ,60Sec.
- TURN RATIO (±5%) : 1CT : 1CT
- DCR : 1.0Ω MAX.
- OCL : : (@100kHz, 0.1Vrms WITH 15mA DC BIAS) : 120uH MIN.
- CROSS TALK (dB MIN.) : 1-100MHz 100-500MHz
-40 -30
- INSERTION LOSS : 100kHz 1-400MHz 500MHz
-3.0dB MAX. -2.0dB MAX. -3.0dB MAX.
- RETURN LOSS : 1-40MHz 40-500MHz
-18dB MIN -17+10 log(f/40)dB MIN
- DIFFERENTIAL TO COMMON MODE REJECTION (dB MIN.) :
1-250MHz 250-500MHz
-30 -22
- COMPLIANT WITH IEEE 802.3an & 802.3bt STANDARD
- OPERATING TEMPERATURE RANGE :
-40°C to +125°C (90°C MAX, AMBIENT+35°C TEMP,RISE)
- Suitable for End-span PoE applications with 1080mA current

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE ±0.25mm

								TITLE 10G BASE-T PoE+ TRANSFORMER	
								DWG. NO. ATPL-590TPR	
	RELEASE	05/12/2023	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 of 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	DRAW	
REVISIONS						05/12/23			SHIRLEY

3. Package:



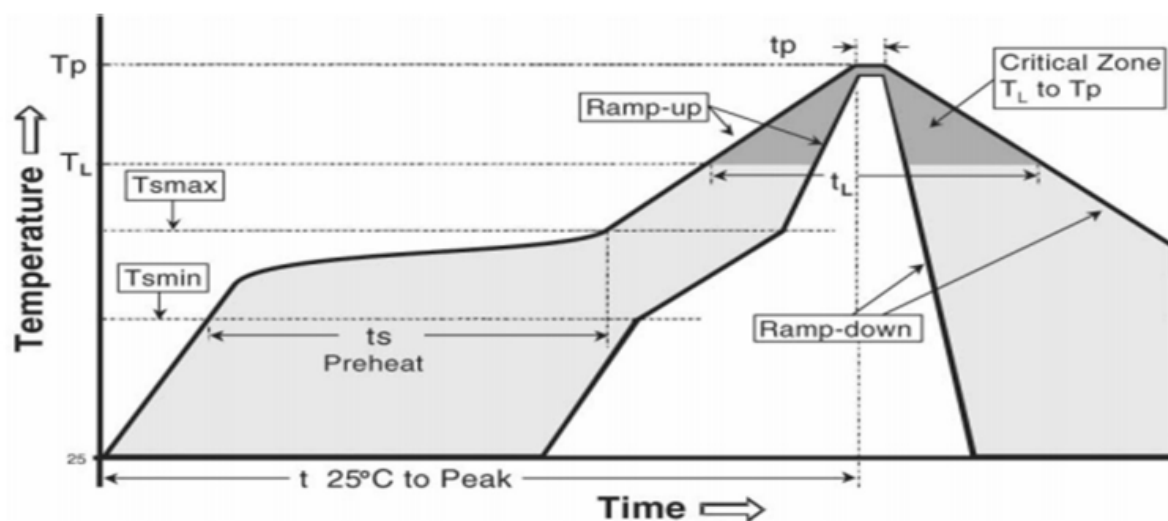
Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 24 PIN Series	400	400x6=2400		1.45

Remarks:

- 1) Packing Level & Storage Condition based on MSL1
- 2) ESD package
- 3) Parts packaging meet EIA-481 standard (pull 0.26N~1.3N)

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmmax)	150°C	200°C
Time (Tsmmin to Tsmmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max